Standardized Information for Process/Product Change Notification (PCN)

		1. PCN ba	asic data	
1.1 Company	TAIWAN SEMICONDUCTOR			
1.2 PCN No.		PCN16030		
1.3 Title of PCN		Assembly Supplier change		
1.4 Product Category		Active Components - Discrete	~	
1.5 Issue date		2017/01/09		
1.6 PCN revision history (optional)		1.7 Issue date of previous revision (optional)	1.8 Delta to previous revision (optional)	

2. PCN Team						
2.1 Contact supplier						
2.1.1 Name	Sunnie Pan					
2.1.2 Phone	+886-2-8913-1588 Ext:2205	+886-2-8913-1588 Ext:2205				
2.1.3 Email	sunnie@mil.ts.com.tw					
2.2 Team supplier (optional)						
2.2.1 Name (optional)	2.2.2 Phone (optional)	2.2.3 Email (optional)				
Danny	886-2-8913-1588 Ext.2133	danny_lin@mail.ts.com.tw				
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	3. Changes						
No.	3.0 Ident	3.1 Category	3.2 Type of change				
#1	SEM-PW-02	PROCESS - WAFER PRODUCTION	New wafer diameter				
#2	SEM-PA-07	PROCESS - ASSEMBLY	Die attach material				
#3	SEM-PA-18	PROCESS - ASSEMBLY	Move of all or part of assembly to a different location/site/subcontractor.				
#4							
#5							

4. Description of change						
	Old	New				
Change #1	Assembly Supplier A	Assembly Supplier B				
Change #2	Wafer : 5"	Wafer : 6"				
Change #3	Die attach material : Soft solder	Die attach material : .Epoxy				
Change #4						
Change #5						
4.6 Anticipated impact on form, fit, function, reliability or processability?	Not impact the form, fit, function, reliability or processat	ility				
4.7 Reference parts with customer number (optional)						

5. Reason / motivation for change			
5.1 Motivation	5" Wafer EOL & Change the subcon		
5.2 Additional explanation (optional)			

6. Marking of parts / traceability of change				
6.1 Description	Use date code to control			

7. Timing / schedule			
7.1 Date of qualification results	2016/11/24		

7.2 Last order date (optional)	2017/05/09	
7.3 Last delivery date (optional)	2018/05/09	
7.4 Intended start of delivery	2017/01/09	
7.5 Qualification samples available?	When get customer order a	and after 2 weeks can be submitted

8. Qualification / validation				
8.1 Description	According to JESD22			
(e.g. qual. plan/report, AEC-Q)				
8.2 Qualification report and qualification	available (see attachement)	issue date	2016/11/24	
results	avaliable (see allachement)			

9. Input to customer for risk assessment process

Human Resource : Low Risk Equipment : Low Risk Technique-Wafer : Low Risk Technique-Assembly : Low Risk Sample submit time : within 30 days Form/ Fit / Function : Low Risk Reliability : Low Risk

10. Attachments (e.g. new datasheet, additional documentation, pictures, process flow, sample plan, ...)
Please see in the official announcement mail.

	11. Affected parts								
11.1 Current				11.2 New (if applicable)					
11.1.1 Customer Part No.	11.1.2 Supplier Part Name	11.1.3 Supplier Part No. (optional)	11.1.4 Package Name	11.1.5 Part Description (optional)	11.1.6 Additional Part Information	11.2.2 Supplier Part Name	11.2.3 Supplier Part No. (optional)	11.2.4 Package Name	11.2.6 Additional Part Information
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Customer Feedback/Approval Form Form Title of PCN: provided by ZVEI - Revision 3.0.0 Assembly Supplier change **Customer PCN** Supplier PCN No. PCN16030 No. Please check the appropriate box below: 1. Feedback date: We agree with this proposed change for the parts as listed in chapter '11. Affected parts'. Approval letter will be sent in written form. We agree with this proposed change schedule and will start with the PCN process. Approval letter will be sent in written form after evaluation. We disapprove because: Remark: 2. Feedback date: We acknowledge qualification / validation as assigned in chapter 8 of the PCN. We need more information: We need the following samples: Estimated closing date for PCN: Final Feedback/Approval date: Sender: Company: Name: Address/Location:

Signature:	
Date:	
	Please return to: [your Sales partner]
Name:	
Address/Location:	
Phone:	
Fax:	
Email:	